

PLASTIC DUAL-IN-LINE PACKAGING (PDIP)  
HAVING ENHANCED HEAT DISSIPATION

5

ABSTRACT OF THE DISCLOSURE

According to one embodiment, an electronic device comprising a plastic dual-in-line packaging (PDIP) package structure is provided. The PDIP package structure includes a mold structure, a die disposed within the mold structure, and a die attach pad coupled to the die. The die attach pad has a first surface exposed from the mold structure.

10